Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	18	(flip near2 chip) and (solder near2 (ball or joint$3)) and bump and c4 and (controlled near2 collapse near2 bond$3)	USPAT	OR	OFF	2005/02/28 13:32
S3	8934	((257/678,684,700-703,734,737, 777,778,779,782,786) or (361/679, 748,820)).CCLS.	USPAT; USOCR	OR	OFF	2005/02/28 14:01
S5	3767	(257/737,778,738,786).CCLS.	USPAT; USOCR	OR	OFF	2005/02/28 14:17
S6	2	(("6046499") or ("5120678")).PN.	USPAT; USOCR	OR	OFF	2005/02/28 14:08
S7	1841	(257/738,737).CCLS.	USPAT; USOCR	OR	OFF	2005/02/28 14:18
S9	1226	(257/737).CCLS.	USPAT; USOCR	OR	OFF	2005/02/28 14:18
S10	1169	(257/738).CCLS.	USPAT; USOCR	OR	OFF	2005/02/28 14:19
S12	1725	(257/778).CCLS.	USPAT; USOCR	OR	OFF	2005/03/01 11:05
S13	1183	(257/786).CCLS.	USPAT; USOCR	OR	OFF	2005/02/28 16:10
S15	40	(flip near2 chip) and bump$2 near3 reinforc$4	USPAT	OR	OFF	2005/02/28 16:13
S16	41	(US-5629835-$ or US-6163463-$ or US-5795818-$ or US-6404062-$ or US-6858799-$ or US-6856028-$ or US-6825567-$ or US-6787924-$ or US-6787921-$ or US-6781245-$ or US-6756684-$ or US-6667557-$ or US-6605492-$ or US-6528889-$ or US-6479903-$ or US-6476486-$ or US-6410988-$ or US-6400033-$ or US-6249048-$ or US-6239489-$ or US-6104093-$ or US-6798667-$ or US-6777815-$ or US-6750552-$ or US-6747362-$ or US-6734555-$). did. or (US-6683379-$ or US-6667561-$ or US-6528882-$ or US-6528872-$ or US-6265783-$ or US-6225702-$ or US-6057596-$ or US-5986346-$ or US-5796170-$ or US-5598036-$ or US-3795845-$ or US-6800946-$ or US-6578755-$ or US-6107685-$ or US-5120678-$). did.	USPAT	OR	OFF	2005/03/01 10:01
S17	1	("5894410").PN.	USPAT; USOCR	OR	OFF	2005/03/01 10:32

S19	1635	(flip near2 chip) and (solder near2 (ball or joint$2)) and bump	USPAT	OR	OFF	2005/03/02 09:01
S32	1635	(flip near2 chip) and (solder near2 (ball or joint$2)) and bump	USPAT	OR	OFF	2005/03/02 09:03
S33	330	S32 and ring	USPAT	OR	OFF	2005/03/02 11:57
S36	1015	S32 and (epoxy)	USPAT	OR	OFF	2005/03/02 10:41
S37	1	"6605492".pn.	USPAT	OR	OFF	2005/03/02 09:31
S38	30	S32 and (epoxy near2 (ball or bump))	USPAT	OR	OFF	2005/03/02 09:48
S41	1635	(flip near2 chip) and (solder near2 (ball or joint$2)) and bump	USPAT	OR	OFF	2005/03/02 11:58
S42	19	S41 and (ring near4 (bump or ball))	USPAT	OR	OFF	2005/03/02 11:58
S44	2	("20030060035").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/30 10:18
S45	9	"257"/$.ccls. and (dummy with reinforc$3 with bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:21